Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	145	257/930.ccls. and (@ad<"19980831")	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/24 14:49
L2	1	L1 and flip	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/24 14:01
L3	0	pelter and (flip near (chip or die)) and (@ad<"19980831")	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/24 15:46
L4	23	peltier and (flip near (chip or die)) and (@ad<"19980831")	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/24 14:48
L5	361	(peltier with (heat or heating)) and (chip or die) and (@ad<"19980831")	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/24 15:20
L6	361	L5 and (@ad<"19980831")	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/24 15:54
L7	109	(peltier with ((heat or heating) and (chip or die))) and (@ad<"19980831")	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/24 14:50
L8	14	L7 and ((substrate or board or interposer or pwb or pcb) with ("si" or silicon))	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/24 14:51
L9	32	("5229327").URPN.	USPAT	OR	OFF	2005/02/24 14:58

L10	73	("3923567" | "3959047" | "3982268" | "4081701" | "4394712" | "4595428" | "4631636" | "4653025" | "4710798" | "4713841" | "4739446" | "4870470" | "4977439" | "5061987" | "5079618" | "5153814" | "5168334" | "5229327" | "5258648" | "5275001" | "5313361" | "5317197" | "5343366" | "5352998" | "5362976" | "5392407" | "5409547" | "5415699" | "5432823" | "5438224" | "5468681" | "5532506" | "5567654" | "5574923" | "5587119" | "5598031" | "5598039" | "5610366" | "5618752" | "5622875" | "5633962" | "5637828" | "5646067" | "5656548" | "5657481" | "5682062" | "5692558" | "5699073" | "5699291" | "5714791" | "5747728" | "5753529" | "5767001" | "5781746" | "5786628" | "5807783" | "5821624" | "5834799" | "5855735" | "5861666" | "5901050" | "5902118" | "5903018" | "5903045" | "5915167" | "5990550" | "5990564" | "5991161" | "6016256" | "6137164" | "6219237" | "6223273" | "6281042").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/02/24 15:20
L11	356	L6 not L10	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/24 15:21
L12	1697	((substrate or board or interposer or pwb or pcb) with ("si" or silicon)) and (flip near (chip or die)) and (@ad<"19980831")	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/24 15:46
L13	860	((substrate or board or interposer or pwb or pcb) near ("si" or silicon)) and (flip near (chip or die)) and (@ad<"19980831")	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/24 15:53

L14	246	((micromachined or micromachine or micromaching or (micro near machine$3)) with (via or hole))	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/24 15:54
L15	95	L14 and (@ad<"19980831")	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/24 15:55
L16	0	L13 and L15	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/24 15:55